Trench Small Signal MOSFET

20 V, 0.88 A, Dual P-Channel, ESD Protected SC-88

Features

- Leading Trench Technology for Low R_{DS(ON)} Performance
- Small Footprint Package (SC70–6 Equivalent)
- ESD Protected Gate
- NV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices

Applications

- Load/Power Management
- Charging Circuits
- Load Switching
- Cell Phones, Computing, Digital Cameras, MP3s and PDAs

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Parameter			Symbol	Value	Unit	
Drain-to-Source Voltage			V_{DSS}	-20	V	
Gate-to-Source Voltage)		V_{GS}	±12	V	
Continuous Drain	Steady	T _A = 25°C	I _D	-0.88	Α	
Current (Note 1)	State	T _A = 85°C		-0.63		
Power Dissipation	Steady	T _A = 25°C	P _D	0.272	W	
(Note 1)	State	T _A = 85°C		0.141		
Continuous Drain	t ≤ 5 s	T _A = 25°C	I _D	-1.0	Α	
Current (Note 2)		T _A = 85°C		-0.72		
Power Dissipation	t ≤ 5 s	T _A = 25°C	P_{D}	0.35	W	
(Note 2)		T _A = 85°C		0.181		
Pulsed Drain Current t ≤ 10 μs			I _{DM}	±3.0	Α	
Operating Junction and Storage Temperature			T _J , T _{STG}	-55 to 150	°C	
Continuous Source Current (Body Diode)			IS	-0.48	Α	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C	

THERMAL RESISTANCE RATINGS (Note 1)

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State	$R_{\theta JA}$	460	°C/W
Junction-to-Ambient - t ≤ 5 s	$R_{\theta JA}$	357	
Junction-to-Lead - Steady State	$R_{\theta JL}$	226	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

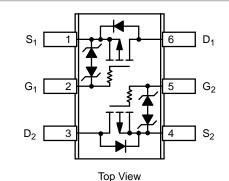
- 1. Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces), steady state.
- Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces), t ≤ 5 s.



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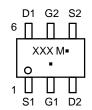
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V _{(BR)DSS}	R _{DS(on)} Typ	I _D Max
	215 m Ω @ -4.5 V	
–20 V	345 mΩ @ –2.5 V	-0.88 A
	600 mΩ @ –1.8 V	



MARKING DIAGRAM & PIN ASSIGNMENT





XXX = Device Code

M = Date Code

Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J=25°C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V, } I_D = -250 \mu\text{A}$		-20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = -16 V	$T_J = 25^{\circ}C$			-1.0	μΑ
			T _J = 125°C		-1.0	-5.0	
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = 0$	±4.5 V		0.03	1.0	μΑ
		V _{DS} = 0 V, V _{GS} = :	±12 V		6.0		
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = -2$	250 μΑ	-0.45		-1.2	V
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -4.5 \text{ V}$	-0.88 A		215	260	mΩ
		$V_{GS} = -2.5 \text{ V}, I_D = -2.5 \text{ V}$	-0.71 A		345	500	
		$V_{GS} = -1.8 \text{ V}, I_D = -0.20 \text{ A}$			600	1000	
Forward Transconductance	9FS	$V_{DS} = -10 \text{ V}, I_D = -0.88 \text{ A}$			3.0		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{ISS}				155		pF
Output Capacitance	C _{OSS}	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = -20 \text{ V}$			25		1
Reverse Transfer Capacitance	C _{RSS}	. 53 =0 .	•		18		1
Total Gate Charge	Q _{G(TOT)}				2.2		nC
Gate-to-Source Charge	Q_{GS}	$V_{GS} = -4.5 \text{ V}, V_{DS} = I_{D} = -0.88 \text{ A}$	–10 V,		0.5		1
Gate-to-Drain Charge	Q_{GD}	1 _D = 0.0071			0.65		1
SWITCHING CHARACTERISTICS (No	ote 4)				•	•	
Turn-On Delay Time	t _{d(ON)}				5.8		ns
Rise Time	t _r	V _{GS} = -4.5 V, V _{DD} =	-10 V,		6.5		1
Turn-Off Delay Time	t _{d(OFF)}	$V_{GS} = -4.5 \text{ V}, V_{DD} = -10 \text{ V},$ $I_{D} = -0.5 \text{ A}, R_{G} = 20 \Omega$			13.5		1
Fall Time	t _f				3.5		
DRAIN-SOURCE DIODE CHARACTE	RISTICS				•	•	•
Forward Diode Voltage	V _{SD}	$V_{GS} = 0 V$.	T _J = 25°C		-0.8	-1.2	V
		$V_{GS} = 0 \text{ V},$ $I_{S} = -0.48 \text{ A}$	T _J = 125°C		-0.66		1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width ≤ 300μs, duty cycle ≤ 2%.

4. Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

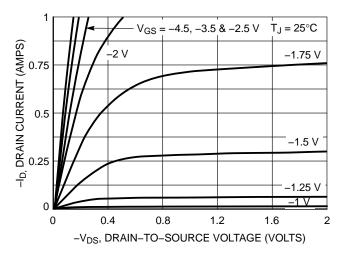


Figure 1. On-Region Characteristics

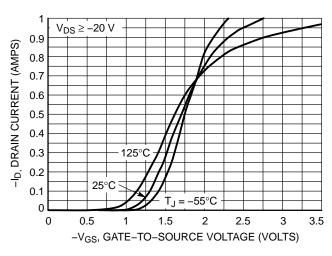


Figure 2. Transfer Characteristics

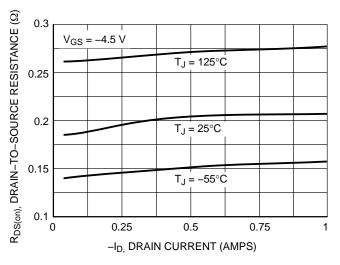


Figure 3. On–Resistance vs. Drain Current and Temperature

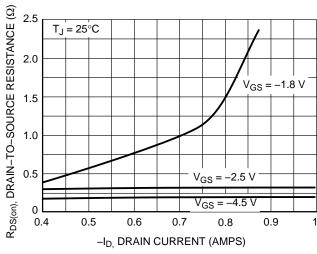


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

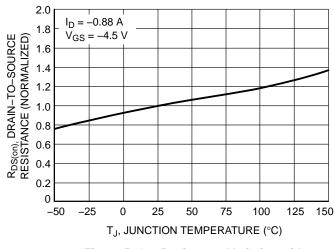


Figure 5. On–Resistance Variation with Temperature

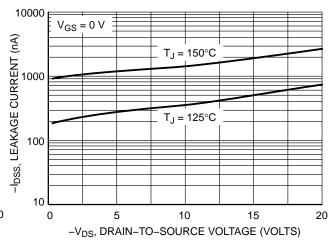


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

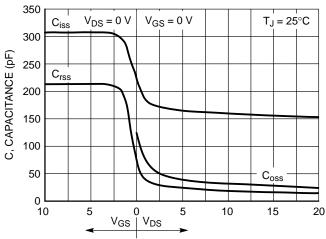
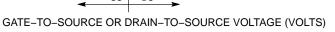


Figure 7. Capacitance Variation



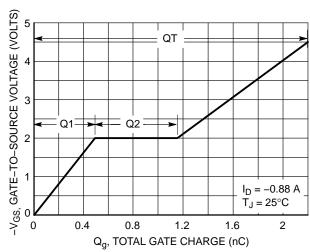


Figure 8. Gate-to-Source Voltage vs. Total **Gate Charge**

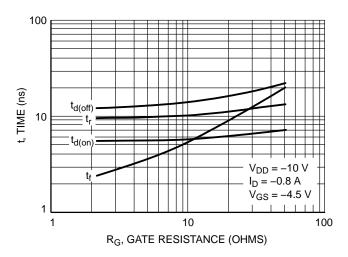


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

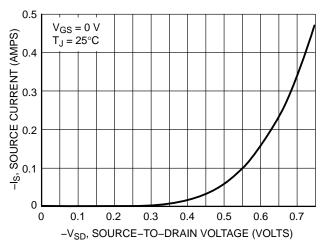


Figure 10. Diode Forward Voltage vs. Current

ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTJD4152PT1G	TK		
NTJD4152PT2G	TK	SC-88 (Pb-Free)	3000 / Tape & Reel
NVJD4152PT1G*	VTK	(1 1 1 2 3)	

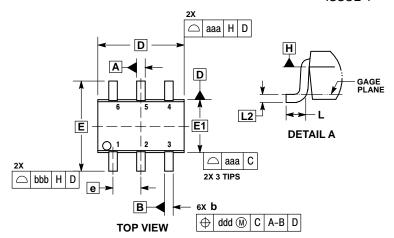
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

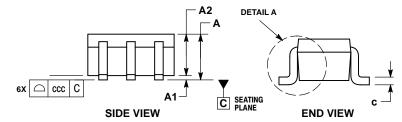
^{*}NV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363

CASE 419B-02 ISSUE Y





- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRU-SIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
- DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF
- THE PLASTIC BODY AND DATUM H.

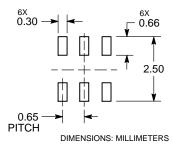
 DATUMS A AND B ARE DETERMINED AT DATUM H.

 DIMENSIONS b AND CAPPLY TO THE FLAT SECTION OF THE

 LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
- DIMENSION 5 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			1.10			0.043
A1	0.00		0.10	0.000		0.004
A2	0.70	0.90	1.00	0.027	0.035	0.039
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.070	0.078	0.086
E	2.00	2.10	2.20	0.078	0.082	0.086
E1	1.15	1.25	1.35	0.045	0.049	0.053
е		0.65 BS	С	0.026 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018
L2	0.15 BSC			(0.006 BS	SC
aaa	0.15				0.006	
bbb	0.30			0.012		
ccc	0.10			0.004		
ddd	0.10			0.004		

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 DRAIN 1

STYLE 26: PIN 1. SOURCE 1

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Contact Us:

> Address:

401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd Minhang District, Shanghai , China

> Sales:

Direct +86 (21) 6401-6692

Email amall@ameya360.com

QQ 800077892

Skype ameyasales1 ameyasales2

Customer Service :

Email service@ameya360.com

Partnership :

Tel +86 (21) 64016692-8333

Email mkt@ameya360.com